



Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL BC-0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_S2150_TCoil_CELL_Ch.1013 z (axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 53.5 dB

ABM1 comp = 0.404 dB A/m

BWC Factor = 0.155041 dB

Location: 1.3, 0, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

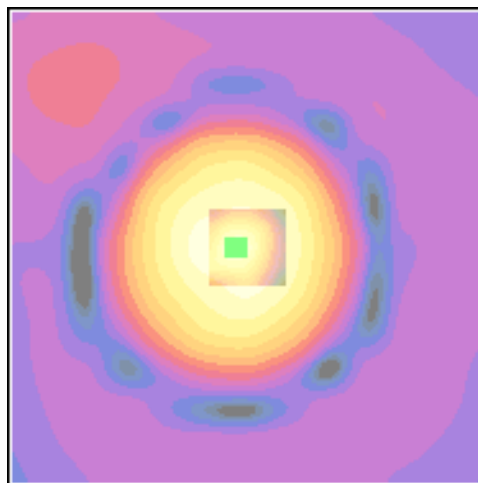
Cursor:

ABM1/ABM2 = 53.8 dB

ABM1 comp = 0.709 dB A/m

BWC Factor = 0.155041 dB

Location: 1.2, 0, 3.7 mm



0 dB = 475.0

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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_S2150_TCoil_CELL_Ch. 1013 x (longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.0 dB

ABM1 comp = -7.37 dB A/m

BWC Factor = 0.155041 dB

Location: -5.4, -3.3, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

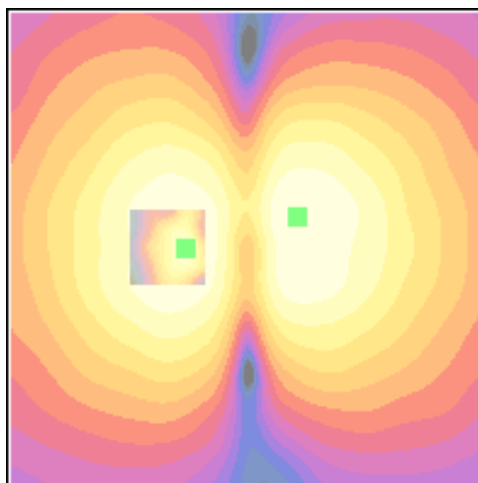
Cursor:

ABM1/ABM2 = 50.2 dB

ABM1 comp = -7.94 dB A/m

BWC Factor = 0.155041 dB

Location: 6.5, 0.2, 3.7 mm



0 dB = 316.7

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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_S2150_TCoil_CELL_Ch. 1013 y (transversal)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -8.15 dB A/m

BWC Factor = 0.155041 dB

Location: 0.4, -6.7, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

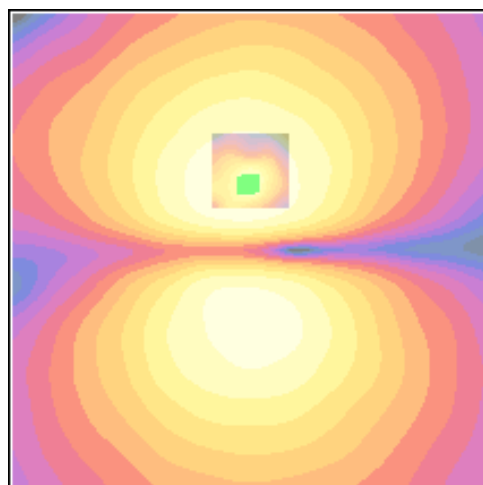
Cursor:

ABM1/ABM2 = 49.7 dB

ABM1 comp = -7.91 dB A/m

BWC Factor = 0.155041 dB

Location: 0, -6.9, 3.7 mm



0 dB = 298.7

Applicant	Kyocera
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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_ S2150_TCoil_CELL_Ch.384 z (axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 53.2 dB

ABM1 comp = 0.353 dB A/m

BWC Factor = 0.155979 dB

Location: 1.7, 0, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

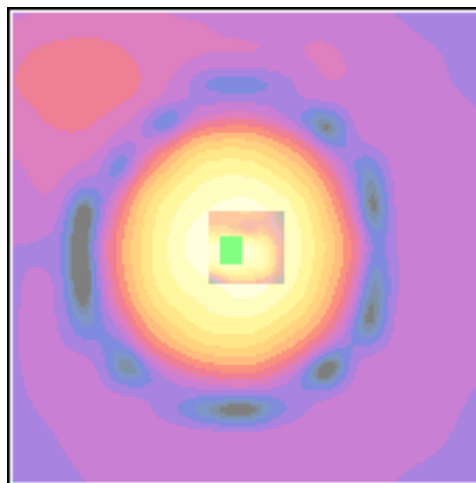
Cursor:

ABM1/ABM2 = 53.3 dB

ABM1 comp = 0.137 dB A/m

BWC Factor = 0.155979 dB

Location: 1.6, 0.6, 3.7 mm



0 dB = 458.9

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FCC ID:	V65S2150
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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_S2150_TCoil_CELL_Ch.384 x (longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -7.86 dB A/m

BWC Factor = 0.155979 dB

Location: -5.8, 0, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

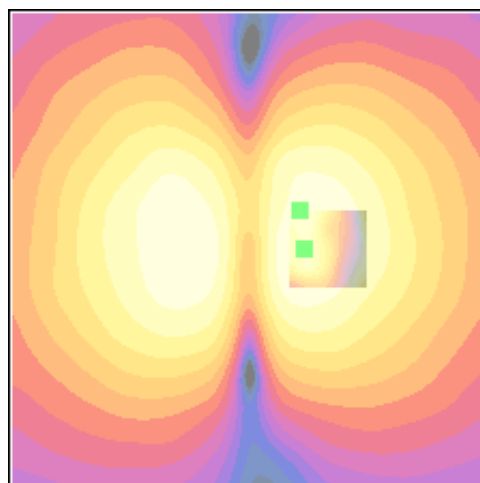
Cursor:

ABM1/ABM2 = 50.4 dB

ABM1 comp = -7.47 dB A/m

BWC Factor = 0.155979 dB

Location: -5.3, -4, 3.7 mm



0 dB = 326.0

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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_S2150_TCoil_CELL_Ch.384 y(transversal)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.8 dB

ABM1 comp = -7.74 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -7.5, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

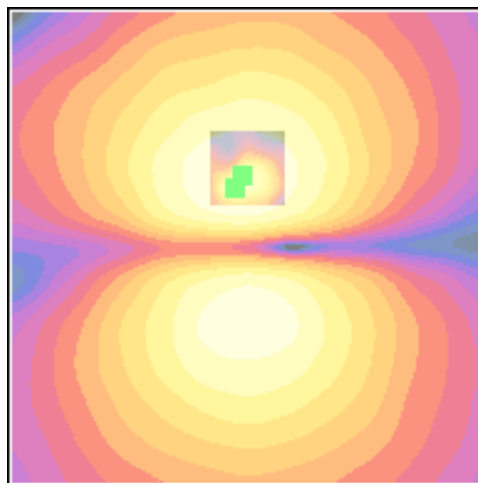
Cursor:

ABM1/ABM2 = 49.7 dB

ABM1 comp = -8.04 dB A/m

BWC Factor = 0.155979 dB

Location: 1.4, -6.3, 3.7 mm



0 dB = 308.9

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Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_ S2150_TCoil_CELL_Ch. 777 z(axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.6 dB

ABM1 comp = -0.304 dB A/m

BWC Factor = 0.155979 dB

Location: 1.7, 0.4, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

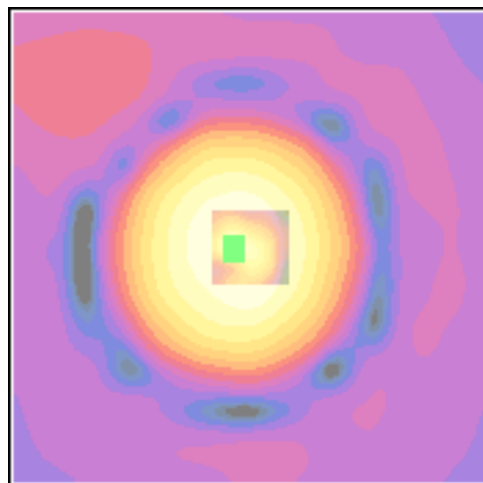
Cursor:

ABM1/ABM2 = 53.5 dB

ABM1 comp = 0.650 dB A/m

BWC Factor = 0.155979 dB

Location: 1.8, -0.2, 3.7 mm



0 dB = 426.6

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_ S2150_TCoil_CELL_Ch. 777 x(longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527,Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.5 dB

ABM1 comp = -7.65 dB A/m

BWC Factor = 0.155979 dB

Location: -5.4, 0, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

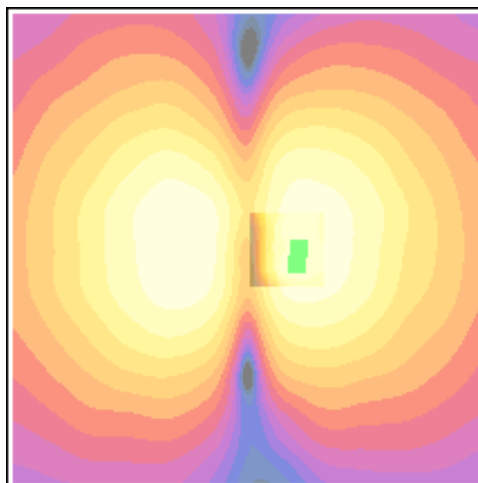
Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -7.87 dB A/m

BWC Factor = 0.155979 dB

Location: -5.2, 1.6, 3.7 mm



0 dB = 335.6

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/19/2012

FCC_ S2150_TCoil_CELL_Ch. 777 y(transveral)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.6 dB

ABM1 comp = -8.15 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -7.1, 3.7 mm

General Scans_777/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

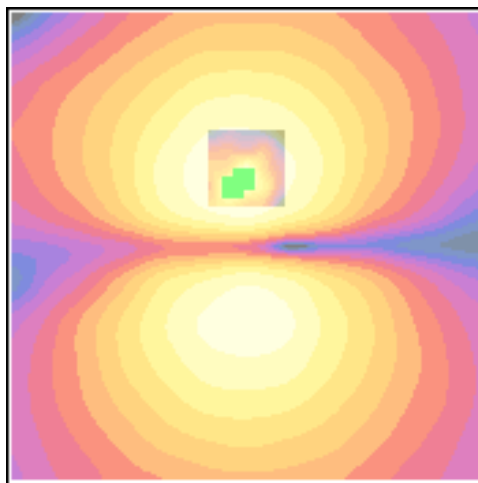
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -7.93 dB A/m

BWC Factor = 0.155979 dB

Location: 1.4, -6.3, 3.7 mm



0 dB = 302.0

Applicant	Kyocera
FCC ID:	V65S2150
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AWS

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_AWS Ch. 25 z(axial)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.1 dB

ABM1 comp = -0.381 dB A/m

BWC Factor = 0.155979 dB

Location: 2.9, 0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

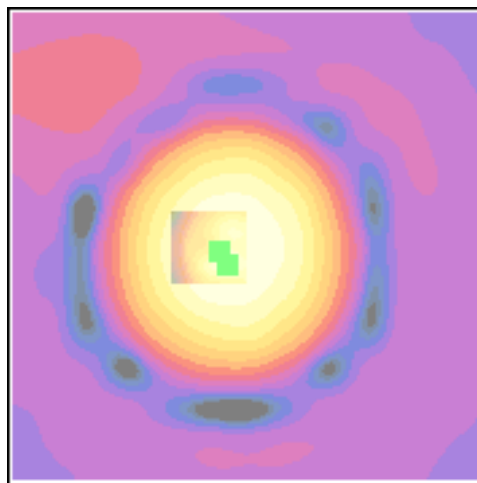
Cursor:

ABM1/ABM2 = 52.7 dB

ABM1 comp = 0.128 dB A/m

BWC Factor = 0.155979 dB

Location: 2.2, 1.8, 3.7 mm



0 dB = 404.1

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Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_AWS_Ch. 25 x(longitudinal)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.2 dB

ABM1 comp = -7.85 dB A/m

BWC Factor = 0.155979 dB

Location: -5.8, -0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

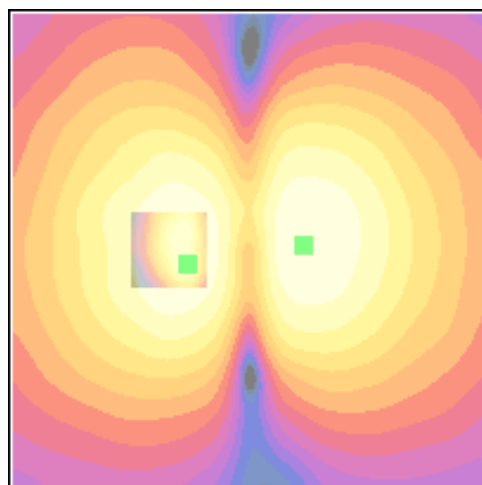
Cursor:

ABM1/ABM2 = 50.1 dB

ABM1 comp = -7.88 dB A/m

BWC Factor = 0.155979 dB

Location: 6.5, 1.6, 3.7 mm



0 dB = 324.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_AWS_Ch. 25 y(transveral)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -8.25 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -5.8, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

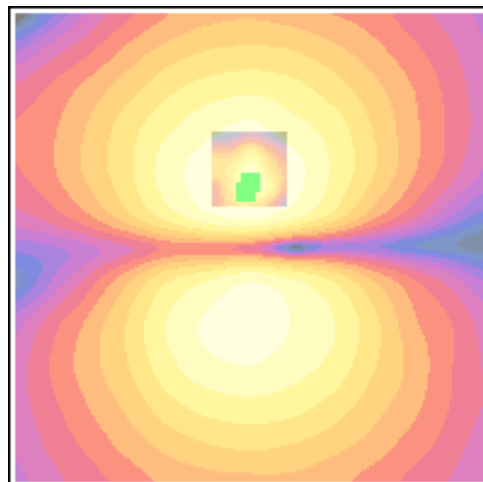
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -8.12 dB A/m

BWC Factor = 0.155979 dB

Location: 0, -6.9, 3.7 mm



0 dB = 292.8

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_AWS Ch. 450 z(axial)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 \pm 1 deg C, Liquid T = 22.0 \pm 1 deg C

General Scans_ 450/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.5 dB

ABM1 comp = -0.322 dB A/m

BWC Factor = 0.155041 dB

Location: 2.9, 0, 3.7 mm

General Scans_ 450/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

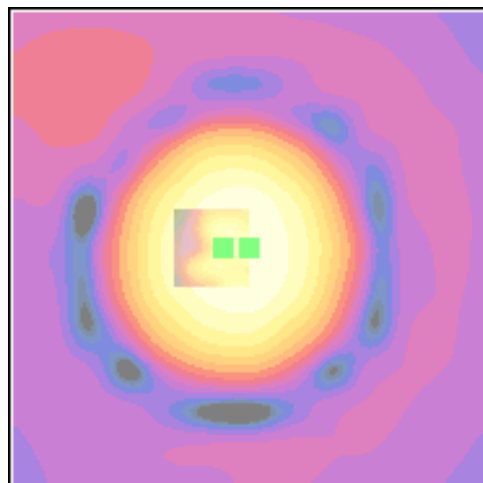
Cursor:

ABM1/ABM2 = 51.8 dB

ABM1 comp = -0.448 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, 0, 3.7 mm



0 dB = 374.5



Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_AWS_Ch. 450 x(longitudinal)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527,Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 450/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.9 dB

ABM1 comp = -7.87 dB A/m

BWC Factor = 0.155041 dB

Location: -5.8, -0.4, 3.7 mm

General Scans_ 450/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

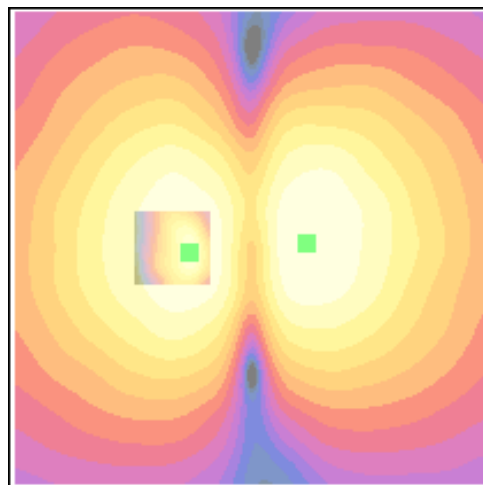
Cursor:

ABM1/ABM2 = 50.1 dB

ABM1 comp = -7.70 dB A/m

BWC Factor = 0.155041 dB

Location: 6.5, 0.6, 3.7 mm



0 dB = 313.2

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_AWS_Ch. 450 y(transveral)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_450/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.0 dB

ABM1 comp = -8.42 dB A/m

BWC Factor = 0.155041 dB

Location: 0, -6.7, 3.7 mm

General Scans_450/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

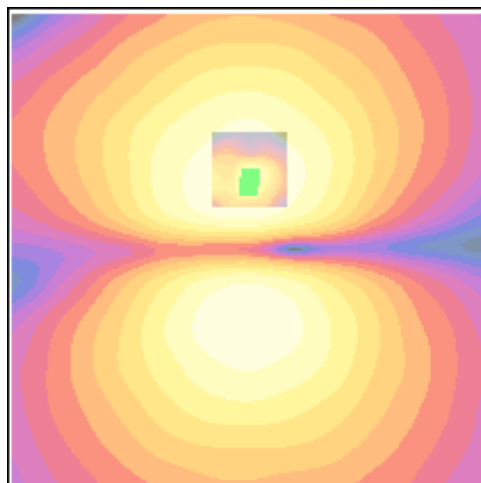
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -8.02 dB A/m

BWC Factor = 0.155041 dB

Location: -0.2, -7.5, 3.7 mm



0 dB = 283.1

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_AWS Ch. 875 z(axial)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 875/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.6 dB

ABM1 comp = -0.537 dB A/m

BWC Factor = 0.155041 dB

Location: 3.3, 0.4, 3.7 mm

General Scans_ 875/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

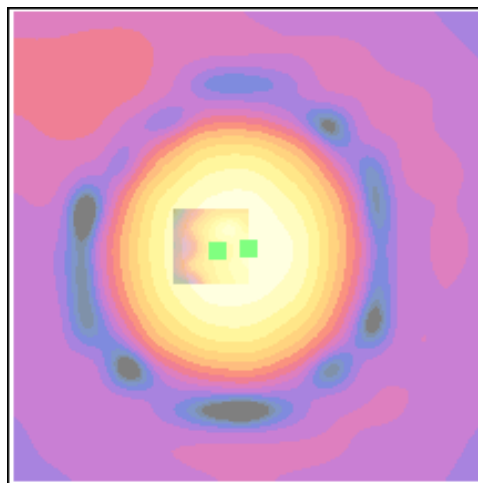
Cursor:

ABM1/ABM2 = 52.3 dB

ABM1 comp = -0.294 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, 0.2, 3.7 mm



0 dB = 380.5

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_AWS_Ch. 875 x(longitudinal)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_875/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.4 dB

ABM1 comp = -7.48 dB A/m

BWC Factor = 0.155041 dB

Location: -5.4, -0.4, 3.7 mm

General Scans_875/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

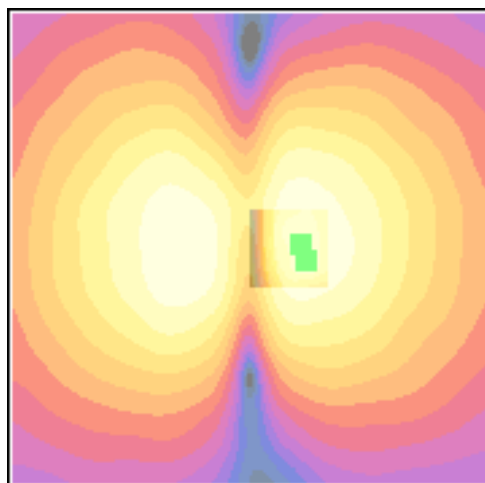
Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -7.66 dB A/m

BWC Factor = 0.155041 dB

Location: -6.2, 1.4, 3.7 mm



0 dB = 330.9

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_AWS_Ch. 875 y(transveral)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_875/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.7 dB

ABM1 comp = -7.87 dB A/m

BWC Factor = 0.155041 dB

Location: 0.8, -7.1, 3.7 mm

General Scans_875/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

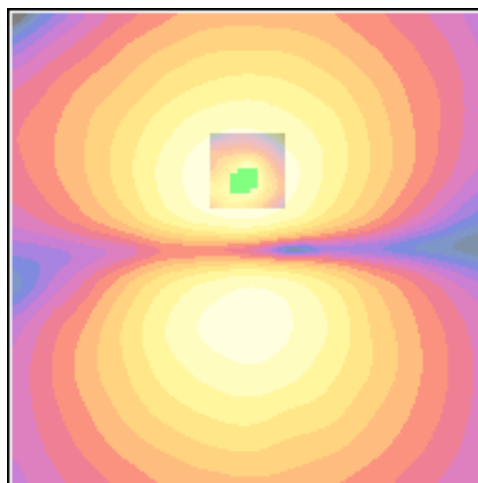
Cursor:

ABM1/ABM2 = 49.8 dB

ABM1 comp = -7.78 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, -7.5, 3.7 mm



0 dB = 306.8

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

PCS

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS_Ch. 25 z(axial)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.9 dB

ABM1 comp = -0.088 dB A/m

BWC Factor = 0.155041 dB

Location: 2.5, 0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

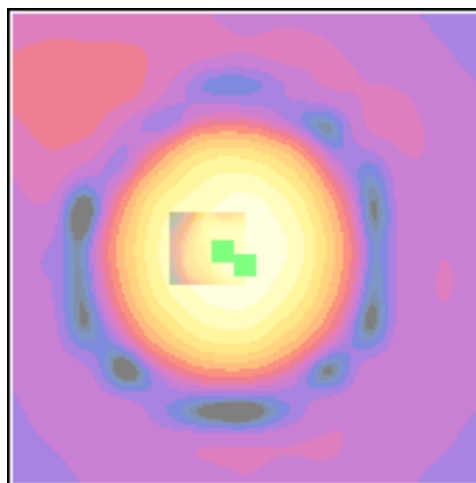
Cursor:

ABM1/ABM2 = 52.4 dB

ABM1 comp = -0.455 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, 1.8, 3.7 mm



0 dB = 392.2

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_PCS_Ch. 25 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.1 dB

ABM1 comp = -7.83 dB A/m

BWC Factor = 0.155041 dB

Location: -5, -0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

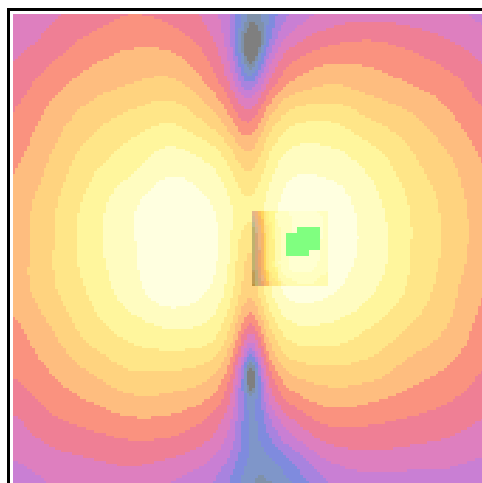
Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -7.62 dB A/m

BWC Factor = 0.155041 dB

Location: -6.2, -1, 3.7 mm



0 dB = 318.1

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS_ Ch. 25 y(transversal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.8 dB

ABM1 comp = -9.17 dB A/m

BWC Factor = 0.155041 dB

Location: 0.8, -5.8, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

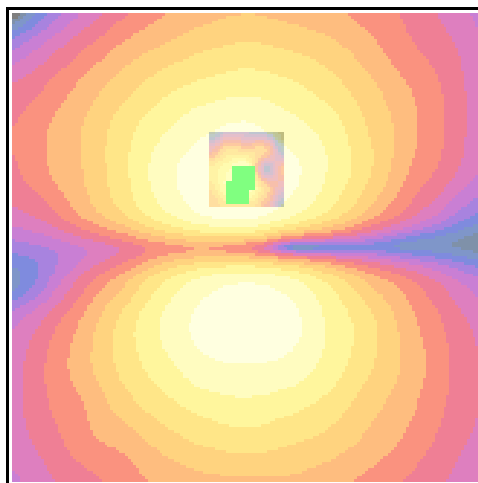
Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -8.58 dB A/m

BWC Factor = 0.155041 dB

Location: 0.4, -7.5, 3.7 mm



0 dB = 276.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS Ch. 600 z(axial)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.6 dB

ABM1 comp = -1.10 dB A/m

BWC Factor = 0.155041 dB

Location: 1.3, 2.1, 3.7 mm

General Scans_ 600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

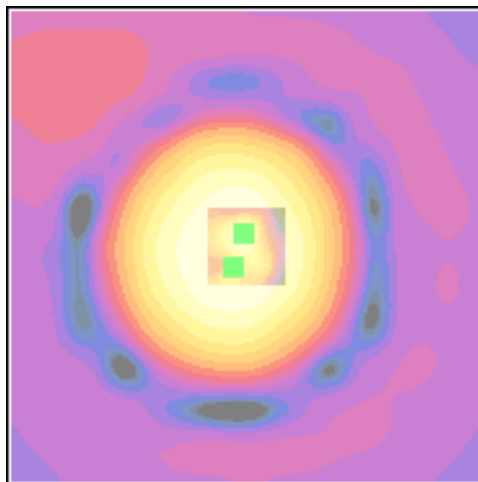
Cursor:

ABM1/ABM2 = 52.3 dB

ABM1 comp = -0.555 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, -1.4, 3.7 mm



0 dB = 378.7

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS Ch. 600 x (longitudinal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn527, Calibrated: 7/30/2012
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

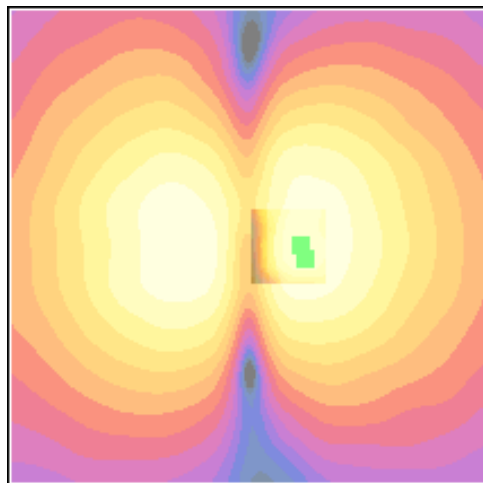
ABM1/ABM2 = 50.7 dB
 ABM1 comp = -7.45 dB A/m
 BWC Factor = 0.155041 dB
 Location: -5.4, 0, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155041 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.4 dB
 ABM1 comp = -7.65 dB A/m
 BWC Factor = 0.155041 dB
 Location: -6, 1.2, 3.7 mm



0 dB = 343.8



Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS_ Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB

ABM1 comp = -8.60 dB A/m

BWC Factor = 0.155041 dB

Location: 0, -5.8, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

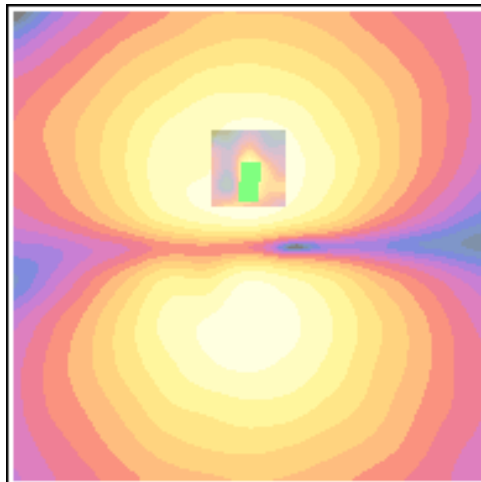
Cursor:

ABM1/ABM2 = 49.2 dB

ABM1 comp = -8.32 dB A/m

BWC Factor = 0.155041 dB

Location: -0.2, -7.9, 3.7 mm



0 dB = 272.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS_ Ch.1175 z(axial)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.0 dB

ABM1 comp = -0.199 dB A/m

BWC Factor = 0.157003 dB

Location: 0.8, 1.2, 3.7 mm

General Scans_ 1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

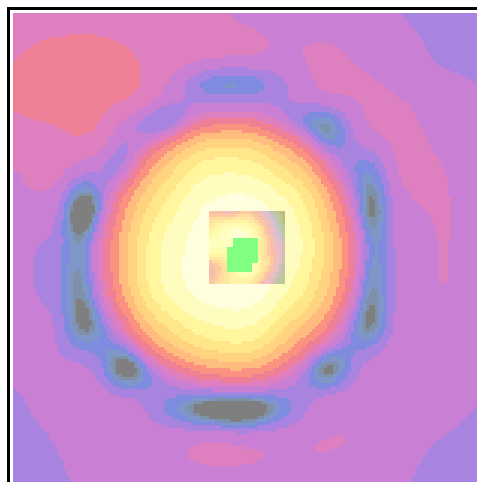
Cursor:

ABM1/ABM2 = 52.6 dB

ABM1 comp = -0.124 dB A/m

BWC Factor = 0.157003 dB

Location: 0.2, 0.4, 3.7 mm



0 dB = 398.6

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_S2150_TCoil_PCS_Ch. 1175 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.9 dB

ABM1 comp = -8.04 dB A/m

BWC Factor = 0.157003 dB

Location: -5.8, -0.4, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

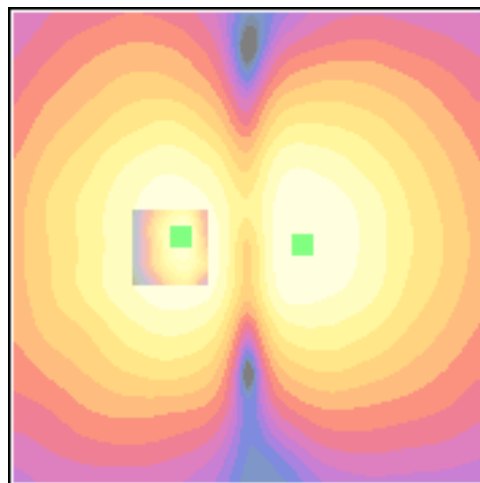
Cursor:

ABM1/ABM2 = 50.1 dB

ABM1 comp = -7.97 dB A/m

BWC Factor = 0.157003 dB

Location: 6.9, -1.2, 3.7 mm



0 dB = 312.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-1112-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 11/15/2012

FCC_ S2150_TCoil_PCS_ Ch. 1175 y(transversal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.3 dB

ABM1 comp = -7.79 dB A/m

BWC Factor = 0.157003 dB

Location: 0, -7.9, 3.7 mm

General Scans_ 1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.157003 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

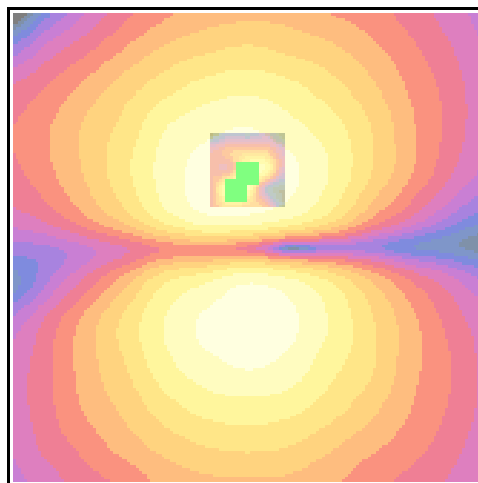
Cursor:

ABM1/ABM2 = 49.5 dB

ABM1 comp = -8.10 dB A/m

BWC Factor = 0.157003 dB

Location: 1.2, -6.3, 3.7 mm



0 dB = 291.8